

Bringing tomorrow's electronics to life



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MRSI Systems (a part of Mycronic Group) is the leading manufacturer of fully automated, high-speed, high-precision, and flexible eutectic and epoxy die bonding systems. We leverage over 40 years of industry expertise in high-accuracy die bonders, active aligners, and fluid dispensers to deliver unparalleled precision and reliability for R&D, NPI, and high-volume manufacturing of photonic devices such as lasers, detectors, modulators, WDM/EML TO-Cans, Optical transceivers, LiDAR, VR/AR, sensors, silicon photonics, co-packaging optics, and optical imaging products. We provide the most flexible assembly solutions for all packaging levels, including chip-on-wafer (CoW), chip-on-carrier (CoC), PCB, and gold-box packaging. Our commitment to excellence ensures we meet our customers' needs with meticulous attention to detail and 24/7 field support. For more information, visit <https://www.mycronic.com/product-areas/die-bonding/>.

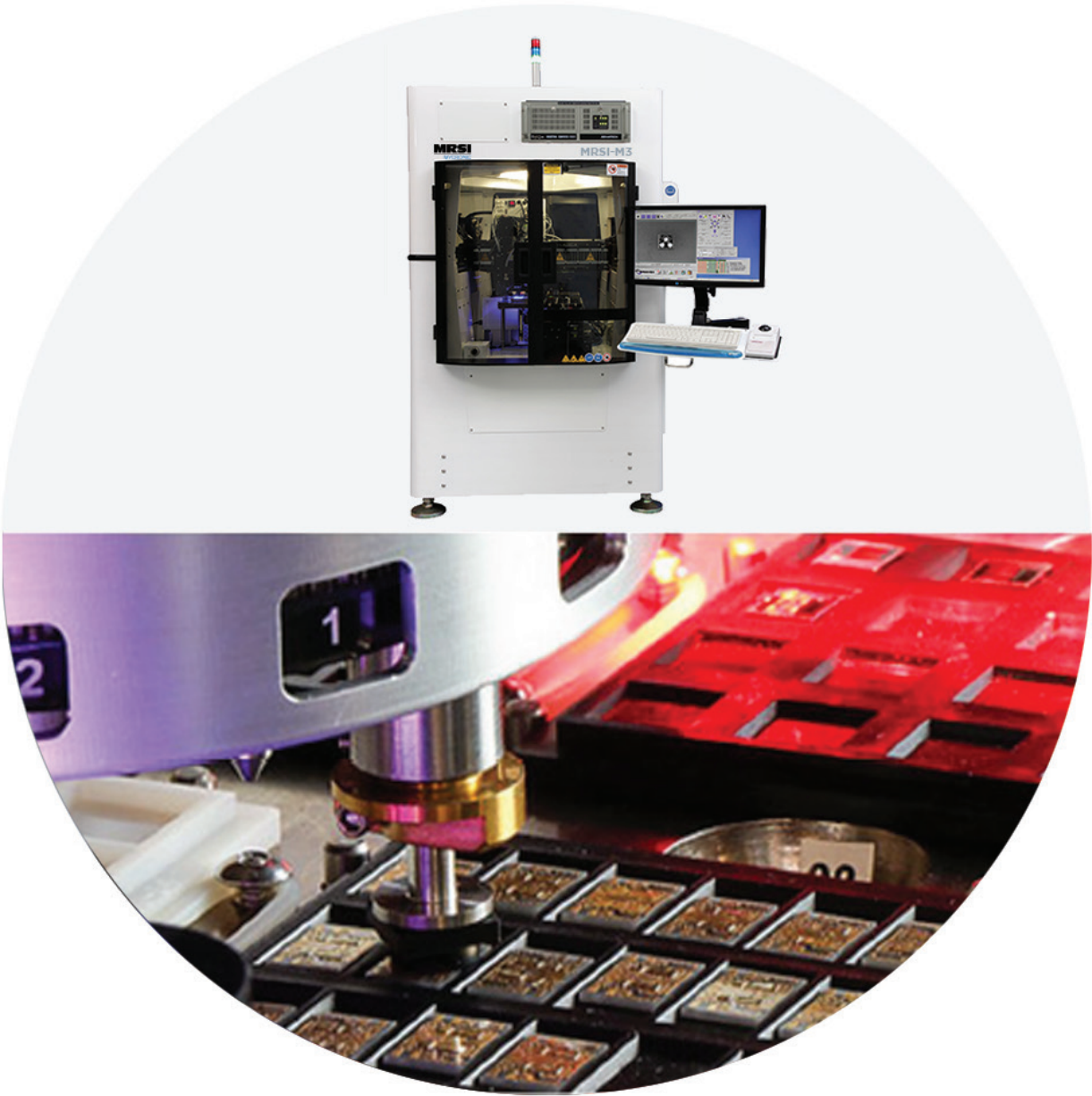
Mycronic is a Swedish high-tech company engaged in the development, manufacture and marketing of production equipment with high precision and flexibility requirements for the electronics industry. Mycronic's headquarters are located in Täby, north of Stockholm and the Group has subsidiaries in China, France, Germany, Japan, Mexico, the Netherlands, Singapore, South Korea, United Kingdom, the United States and Vietnam. Mycronic is listed on Nasdaq Stockholm. www.mycronic.com

Specifications are subject to change without notice.

202506_MRSI-M3V3



MRSI-M3 3 MICRON DIE BONDER



Patented turret for "on-the-fly" tool change

MRSI Systems has been serving optoelectronic and microelectronic customers for the past 40 years and understands their requirement to scale efficiently in today's fast-paced marketplace.

Applications are found across a wide range of market segments, such as life & health sciences, aerospace, defense, automotive, lighting, communications, and more.

MRSI's die bonding solutions help our customers to enable just-in-time supply and fast-paced innovations of critical components for high-growth market segments. The ultra-flexible MRSI-705 and MRSI-M3 can be used for R&D prototyping to low/medium volume.

These die bonding solutions are built with the same hardware and software platforms configured to minimize process deviations, reduce NPI cost, and increase ROI for customers with MRSI's long proven product reliability and global customer support.

MRSI-M3, Highly Configurable



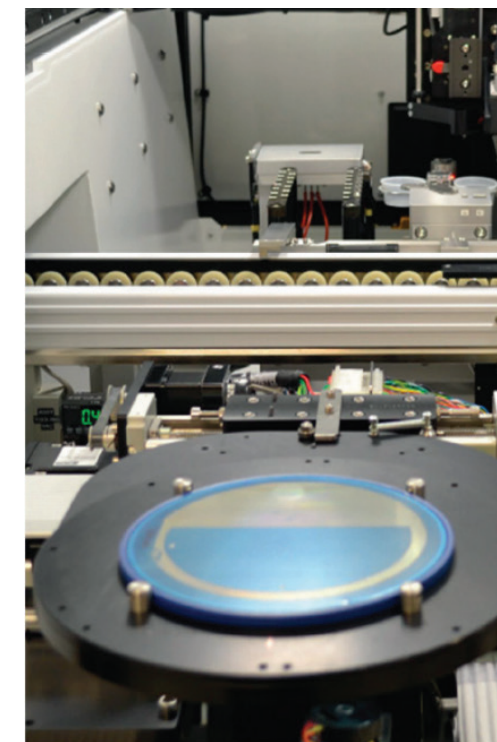
Assembly Technologies

- Eutectic Bonding
- Epoxy Die Attach
- In-situ UV Bonding
- Flip Chip Assembly
- Thermal Compression Bonding



All-In-One Platform

- Large Configurable Work Area
- Force Control for Advanced Assembly
- Advanced Machine Vision
- Programmable Multi-Color Lighting
- Quality Software, Computer and Motion Control
- Turnkey Integrated Production Lines



Configuration for Higher Speed and Volume



The MRSI-M3 offers an optional patented turret for “on-the-fly” tool change to significantly increase the production volume from our machine without sacrificing flexibility. The patented turret has the capacity for 12 tools with zero tool change time.

This leads to increased machine efficiency, higher output and lower manufacturing costs. Applications include processes requiring a large number of parts-specific tools, using eutectic bonding, and the need to assemble complex products with a multitude of component types.



Applications

- 3D Packaging
- Wafer Scale Packaging
- LED Assembly
- Microwave Modules
- Photonics Packaging
- RF Power Amplifiers
- Infrared Sensors
- Pressure Sensors
- MEMS Devices
- Semiconductor Packaging
- Hybrid Circuits
- Multichip Modules
- Pacemakers
- Hearing Aids
- Medical Imaging
- Laser Diode Bonding
- Inkjet and Print Head
- System on a Chip
- System in a Package

